

AW-CM217NF

IEEE 802.11 a/b/g/n/ac Wireless LAN and Bluetooth M.2 Combo Module fidential

Datasheet

AzureWa Version 1.2



Revision History

Revision	Date	Description	Initials	Approved
Version 0.1	2014/11/26	Initial release	Stanley Wang	Chihhao Liac
Version 0.2	2014/12/31	Update Pin definition and Pin Map	Stanley Wang	Chihhao Liac
Version 0.3	2015/2/10	Update Pin definition and Pin Map	Stanley Wang	Chihhao Liao
Version 0.4	2015/2/16	Update Specification	Stanley Wang	Chihhao Liao
Version 0.5	2015/3/31	Update Pin definition, block diagram, and power management	Stanley Wang	Chihhao Liad
Version 0.6	2015/4/15	Update Electrical Characteristics	Stanley Wang	Chihhao Lia
Version 0.7	2015/6/10	Modified- 1-2 Key features 1-3 Block Diagram 1-4 Specifications Table 2-1 Absolute Maximum Ratings 3 Pin Definition	Steven Jian	Chihhao Liad
Version 0.8	2015/8/19	Modified- 2-5-1-1 Bluetooth USB Interface	Steven Jian	Chihhao Lia
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1. Introduction

1.1 Product Overview

AzureWave Technologies, Inc. introduces the advanced **IEEE 802.11** ac/a/b/g/n 2x2 MIMO WLAN and **Bluetooth M.2 combo** module - **AW-CM217NF.** The module is targeted to mobile and embedded devices which need small footprint package, low power consumption, and multiple OS support. The module supports **2.4GHz and 5GHz bands** IEEE 802.11ac MAC/baseband/radio and Bluetooth 5.0 + BLE + EDR. It also features an integrated Power Management Unit (PMU), Power Amplifiers (PAs), and a Low Noise Amplifier (LNA) to address the needs of mobile devices that require minimal power consumption and compact size. By using AW-CM217NF, the customers can easily enable the Wi-Fi and BT embedded applications with the benefits of **high design flexibility, short development cycle, and quick time-to-market.**

For the WLAN operation, the AW-CM217NF uses DSSS, OFDM, DBPSK, DQPSK, CCK and QAM baseband modulation technologies. In IEEE 802.11ac mode, the WLAN operation supports rates of MCS0–MCS9 (up to 256 QAM) in **20 MHz**, **40 MHz**, **and 80 MHz channels** for data rates up to 867 Mbps. A high level of integration and full implementation of the power management functions specified in the IEEE 802.11 standard minimize the system power requirements by using AW-CM217NF. In addition to the support of **WPA/WPA2** (personal) and **WEP** encryption, the AW-CM217NF also supports the IEEE 802.11 is scurity standard through **AES** and **TKIP** acceleration hardware for faster data encryption. For the video, voice and multimedia applications the AW-CM217NF support 802.11e Quality of Service (QoS).

For Bluetooth operation, the AW-CM217NF is **Bluetooth 5.0**. The Bluetooth transmitter also features a Class 1 power amplifier with Class 2 capability. The AW-CM217NF supports **extended Synchronous Connections (eSCO)**, for enhanced voice quality by allowing for retransmission of dropped packets, and **Adaptive Frequency Hopping (AFH)** for reducing radio frequency interference.



1.2 Features

- Integrates CYPRESS solutions of CYW4356 Wi-Fi /BT Single Chip
- Concurrent Bluetooth and WLAN operation
- ECI—enhanced coexistence support, ability to coordinate BT SCO transmissions around WLAN receives
- Multiple power saving modes for low power consumption
- Lead-free /Halogen Free Design
- 12 mm(L) x 16mm(W) x 1.5mm(H) 132 pin LGA package

1.2.1 WLAN

- IEEE 802.11ac Draft compliant
- Full IEEE 802.11a/b/g/n legacy compatibility with enhanced performance
- IEEE 802.11a/b/g/n/ac dual-band radio with virtual-simultaneous dual-band operation
- IEEE 802.11ac 2x2 MIMO supports for 20, 40, and 80 MHz channels with optional SGI (256 QAM modulation) provides data rates up to 866.7 Mbps.
- Tx and Rx low-density parity check (LDPC) support for improved range and power efficiency.
- Supports IEEE 802.15.2 external coexistence interface to optimize bandwidth utilization with other colocated wireless technologies such as LTE, GPS, or WiMAX
- Supports IEEE 802.11d, e, h, i, r, k, w
- WLAN host interface options
 - PCle
- Security–WEP, WPA/WPA2 (personal), AES (HW), TKIP (HW), CKIP (SW).
- WMM/WMM-PS/WMM-SA
- Proprietary protocol –CCXv2/CCXv3/CCXv4/CCXv5
- Integrated CPU with on-chip memory for a complete WLAN subsystem minimizing the need to wake up the applications processor



1.2.2 Bluetooth

- Bluetooth Class 1 or Class 2 transmitter operation
- Supports key features of upcoming Bluetooth standards
- Supports all Bluetooth 4.1 packet types
- **Qualified for Bluetooth 5.0**
- Fully supports Bluetooth Core Specification version 4.1 + (Enhanced Data Rate) EDR features:
 - Adaptive Frequency Hopping (AFH)
 - Quality of Service (QoS)
 - onfidential **Extended Synchronous Connections (eSCO)** — Voice Connections
 - Fast Connect (interlaced page and inquiry scans)
 - Secure Simple Pairing (SSP)
 - Sniff Subrating (SSR)
 - **Encryption Pause Resume (EPR)**
 - **Extended Inquiry Response (EIR)**
 - Link Supervision T imeout (LST)
- Multipoint operation with up to seven active slaves
 - Maximum of seven simultaneous active ACL links
 - Maximum of three simultaneous active SCO and eSCO connections with scatternet support
- Full support for power savings modes
 - **Bluetooth clock request**
 - **Bluetooth standard sniff**
 - Deep-sleep modes and software regulator shutdown
- Wideband speech support (16 bits linear data, MSB first, left justified at 4K samples/s for transparent air coding, both through I2S and PCM interface)
- Multiple simultaneous A2DP audio stream



1.3 Block Diagram

A simplified block diagram of the AW-CM217NF module is depicted in the figure below.

AW-CM217NF Block Diagram T/R Switch 5G WL TX 2G4/5G WLAN BT ANTI 3.3V Supply Diplexe: 2.4G 5G CYW4356 11ac +BT 2G WL_TX T/R Switch USB BT_TX/RX PCTe JTAG WLBGA 5G WL_RX GPIO T/R Switch 5G WL_TX 2G4/5G WLAN ANT2 Diplexes T/R Switch 2G WL_TX XTAL 37.4M Azurev



1.4 Specifications Table

1.4.1 General

Features	Description
Product Description	IEEE 802.11 a/b/g/n/ac Wireless LAN and Bluetooth M.2 Combo Module
Major Chipset	CYPRESS CYW4356
Host Interface	WLAN: PCIe Bluetooth: USB
Dimension	16mm(L) 12xmm(W) x 1.5mm(H)
Package	M.2 1216 Solder down
Antenna	I-PEX MHF4 Connector Receptacle (20449) Ant 1: WiFi/BT Main Ant 2 WIFI AUX
Weight	0.6g

1.4.2 WLAN

Weight	0.09
1.4.2 WLAN	Colle
Features	Description
WLAN Standard	IEEE 802.11a/b/g/n/ac, Wi-Fi compliant
WLAN VID/PID	14E4/43EC
WLAN SVID/SPID	1A3B/2217
Frequency Rage	WLAN: 2.4 GHz / 5GHz Band
Modulation	DSSS DBPSK(1Mbps), DQPSK(2Mbps), CCK(11/5.5Mbps) OFDM BPSK(9/6Mbps/MCS0), QPSK(18/12Mbps/MCS1~2), 16-QAM(36/24Mbps/MCS3~4), 64-QAM(72.2/54/48Mbps/MCS5~7), 256-QAM(MCS8~9)
Number of Channels	802.11b: USA, Canada and Taiwan $-1 \sim 11$ Most European Countries $-1 \sim 13$ Japan $-1 \sim 13$ 802.11g: USA and Canada $-1 \sim 11$ Most European Countries $-1 \sim 13$ 802.11n:



	USA and Canada – 1 ~ 11							
	Most European Countries – 1 ~ 13							
		802.11a:						
		USA – 36, 40, 44, 48, 52, 56, 60, 64, 100, 104, 108, 112, 116, 120,						
		124, 128, 132, 136, 140, 149, 153, 157, 161, 165						
		2.4G						
			Min	Тур	Max	Unit		
		11b (11Mbps) @EVM<35%	14	16	18	dBm		
		11g (54Mbps)	12	14	16	dBm		
		@EVM≦-25 dB	12	17	10			
		11n (HT20 MCS7) @EVM≦-27 dB	11	13	15	dBm		
		11n (HT40 MCS7)	9	11	13	dBm		
Output Power		@EVM≦-27 dB	5		10	dDin		
(Board Level Limit)*		5G						
			Min	Тур	Max	Unit		
		11a (54Mbps)	40		40	alDura		
		@EVM≦-25 dB	12	13	16	dBm		
		11n (HT20 MCS7)	11	12	15	dBm		
		@EVM≦-27 dB		12	15	ubiii		
		11n (HT40 MCS7)	10	10	14	dBm		
		@EVM≦-27 dB						
		11ac (VHT80 MCS9)	6	8	10	dBm		
		©EVM≦-32 dB 0 0 10 dbm 2.4G						
		2.4G	Min	Turn	Max	Linit		
		11b (11Mbpc)	Min	Тур -88	Max -82	Unit dBm		
		11b (11Mbps) 11g (54Mbps)		-74	-62 -68	dBm		
		11n (HT20 MCS7)		-74	-08	dBm		
		11n (HT40 MCS7)		-68	-62	dBm		
Receiver Sensitivity				-00	-02	dbiii		
Receiver Centility		5G						
			Min	Тур	Max	Unit		
		11a (54Mbps)		-73	-67	dBm		
		11n (HT20 MCS7)		-70	-64	dBm		
		11n (HT40 MCS7)		-67	-61	dBm		
		11ac (VHT80 MCS9)		-59	-53	dBm		
		802.11b: 1, 2, 5.5, 11Mb	ps			·		
Data Rate		802.11g: 6, 9, 12, 18, 24, 36, 48, 54Mbps						
		802.11n: MCS0~7 HT20/HT40						
		802.11a: 6, 9, 12, 18, 24, 36, 48, 54Mbps						



	802.11ac: MCS0~8 VHT20 802.11ac: MCS0~9 VHT40/VHT80
Security	 WPA[™]- and WPA2[™]- (Personal) support for powerful encryption and authentication AES and TKIP acceleration hardware for faster data encryption and 802.11i compatibility Secure Easy Setup[™] for simple Wi-Fi® setup and WPA2/WPA security configuration Wi-Fi Protected Setup (WPS) WEP WMM / WMM-SA CKIP(Software)
* If you have any cortification	an questions about output nower please contact EAE directly

If you have any certification questions about output power please contact FAE directly.

1.4.3 Bluetooth

1.4.3 Bluetooth	tial
Features	Description
Bluetooth Standard	Bluetooth 2.1+Enhanced Data Rate (EDR) / BLE/ BT5.0
Bluetooth VID/PID	13D3/3485
Frequency Rage	2400~2483.5MHz
Modulation	GFSK (1Mbps), II/4DQPSK (2Mbps) and 8DPSK (3Mbps)
Output Power	Class 2
Receiver Sensitivity	DH1:-92dBm 2DH5:-94dBm 3DH5:-88dBm

1.4.4 Operating Conditions

Features	Description			
Operating Conditions				
Voltage	power supply for host:3.3V+-5%			
Operating Temperature	-20~85°C (Functionality is guaranteed. Optimal RF operating is 0~55°C)			
Operating Humidity	<85%			
Storage Temperature	-40~85°C			
Storage Humidity	<60 %			



ESD Protection		
Human Body Model	>1kV	
Changed Device Model	>300V	

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2. Pin Definition

2.1 Pin Map

AW-CM217NF Top View Pin Map

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2.2 Pin Table

Pin No	Definition	Basic Description	Voltage	Туре
1	NC	No Connect		
2	JTAG_SEL	JTAG test on/off(pull high to enable JTAG)	VIO	I
3	NC	No Connect		
4	3.3V	3.3V Power Supply	3.3V	I
5	3.3V	3.3V Power supply input	3.3V	I
6	GND	System Ground Pin		
7	JTAG_TDO_GPIO_5	GPIO_5 (input/output)	VIO	0
8	GPIO_8	Strapping option(please pull up with 10k resistor)	VIO	I
9	GPIO_9	Strapping option(please pull up with 10k resistor)	VIO	I
10	JTAG_TDI_GPIO_4	0: SPROM is absent (default). *Please reserve pull-down resistor	VIO	I
11	JTAG_TMS_COEX2_GPIO_3	GPIO_3 (input/output)	VIO	I/O
12	JTAG_TCK_COEX1_GPIO_2	GPIO_2 (input/output)	VIO	I/O
13	JTAG_TRST_N_COEX0_GPIO_6	GPIO_6 (input/output)	VIO	I/O
14	NC	No Connect		
15	NC	No Connect		
16	NC	No Connect		
17	GND	System Ground Pin		
18	NC	No Connect		
19	NC	No Connect		
20	GND	System Ground Pin		
21	NC	No Connect		
22	NC	No Connect		
23	GND	System Ground Pin		
24	BT_DEV_WAKE	No Connect		
25	NC	No Connect		
26	GND	System Ground Pin		
27	SLPCLK	External sleep clock input (32.768 kHz).	0.2~3.3Vp-p	I
28	WL_RFDISABLE_L_GPIO1	WL_DEV_WAKE/GPIO1	VIO	I

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29 30 31 32	PCIE_WAKEn PCIE_CLKREQn PCIE_PERSTn	PCIe wake signal (output) PCIe clock request (input/output)	VIO VIO	0 I/O
31	PCIE_PERSTn		VIO	I/O
32		PCIe host indication to reset the device (input)	VIO	I
	GND	System Ground Pin		
33	PCIE_RCLK_N	PCI Express Differential Clock Input—Negative		I
34	PCIE_RCLK_P	PCI Express Differential Clock Input—Positive		I
35	GND	System Ground Pin		
36	PCIE_TX_N	PCI Express Transmit Data—Negative		0
37	PCIE_TX_P	PCI Express Transmit Data—Positive		0
38	GND	System Ground Pin		
39	PCIE_RX_N	PCI Express Receive Data—Negative		I
40	PCIE_RX_P	PCI Express Receive Data—Positive		I
41	GND	System Ground Pin		
42	NC	No Connect		
43	NC	No Connect		
44	VIO_SD	Logic level for PCIe out-of-band signals.	VIO	I
45	WL_REG_ON	Used by PMU to power up or power down the internal module regulators used by the WLAN section. Also, when deasserted, this pin holds the WLAN section in reset. *This pin is pulled up inside the module	VIO	I
46	SDIO_WAKE_L_GPIO_0	Reserve		
47	SDIO DAT3	Reserve		
48	SDIO DAT2	Reserve		
49	SDIO DAT1	Reserve		
50	SDIO DAT0	Reserve		
51	SDIO CMD	Reserve		
52	SDIO CLK	Reserve		
53	BT_HOST_WAKE	Bluetooth HOST_WAKE.	VIO	0
54	UART CTSn	Reserve		
55	UART SOUT	Reserve		
56	UART SIN	Reserve		

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	Azdrewave Technologi			
57	UART RTSn	Reserve		
58	PCM_SYNC	PCM sync; can be master (output) or slave (input).	VIO	I/O
59	PCM_IN	PCM data input	VIO	I
60	PCM_OUT	PCM data output	VIO	0
61	PCM_CLK	PCM bus clock; can be master (output) or slave (input)	VIO	I/O
62	GND	System Ground Pin		
63	BT_REG_ON	Bluetooth device wake-up: Signal from the host to the AW-CM217NF indicating that the host requires attention. • Asserted: The Bluetooth device must wake-up or remain awake. • Deasserted: The Bluetooth device may sleep when sleep criteria are met. The polarity of this signal is software configurable and can be asserted high or low. *This pin is BT_DEV_WAKE. The original BT_REG_ON is pulled high inside the module and can't be controlled by the host for BT USB mode	VIO	I
64	WL_LED_GPIO_7	It can be used as WL_LED.	VIO	0
65	BT_I2S_DO_BT_LED_L	It can be used as BT_LED.	VIO	0
66	NC	No Connect		
67	NC	No Connect		
68	GND	System Ground Pin		
69	USB_D-	USB Serial Differential Data Negative	3.3V	I/O
70	USB_D+	USB Serial Differential Data Positive	3.3V	I/O
71	GND	System Ground Pin		
72	3.3V	3.3V Power Supply	3.3V	I
73	VIO	Digital I/O Power Supply	VIO	I
74	GND	System Ground Pin		
75	GND	System Ground Pin		
76	GND	System Ground Pin		
77	GND	System Ground Pin		



78	GND	System Ground Pin	
79	GND	System Ground Pin	
80	GND	System Ground Pin	
81	GND	System Ground Pin	
82	GND	System Ground Pin	
83	GND	System Ground Pin	
84	GND	System Ground Pin	
85	GND	System Ground Pin	
86	GND	System Ground Pin	
87	GND	System Ground Pin	
88	GND	System Ground Pin	
89	GND	System Ground Pin	
90	GND	System Ground Pin	
91	GND	System Ground Pin	
92	GND	System Ground Pin	
93	GND	System Ground Pin	
94	GND	System Ground Pin	
95	GND	System Ground Pin	
96	GND	System Ground Pin	
G1	GND	System Ground Pin	
G2	GND	System Ground Pin	
G3	GND	System Ground Pin	
G4	GND	System Ground Pin	
G5	GND	System Ground Pin	
G6	GND	System Ground Pin	
G7	GND	System Ground Pin	
G8	GND	System Ground Pin	
G9	GND	System Ground Pin	
G10	GND	System Ground Pin	
G11	GND	System Ground Pin	

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G12	GND	System Ground Pin
G13	GND	System Ground Pin
G14	GND	System Ground Pin
G15	GND	System Ground Pin
G16	GND	System Ground Pin
G17	GND	System Ground Pin
G18	GND	System Ground Pin
G19	GND	System Ground Pin
G20	GND	System Ground Pin
G21	GND	System Ground Pin
G22	GND	System Ground Pin
G23	GND	System Ground Pin
G24	GND	System Ground Pin
G25	GND	System Ground Pin
G26	GND	System Ground Pin
G27	GND	System Ground Pin
G28	GND	System Ground Pin
G29	GND	System Ground Pin
G30	GND	System Ground Pin
G31	GND	System Ground Pin
G32	GND	System Ground Pin
G33	GND	System Ground Pin
G34	GND	System Ground Pin
G35	GND	System Ground Pin
G36	GND	System Ground Pin



3. Electrical Characteristics

3.1 Absolute Maximum Ratings

Symbol	pol Parameter		Max	Units
3.3V	Power supply for Internal Regulators	-0.3	5.5	v
VIO	DC supply voltage for digital I/O	-0.5	3.9	V

3.2 Recommended Operating Conditions

Symbol	Parameter	Туре	Min	Тур	Max	Units
3.3V	Power supply for Internal Regulators	Input	3.13	-)	3.46	V
3.3 Digital IO Pi	n DC Characteristics	F	9	ns		

3.3 Digital IO Pin DC Characteristics

Symbol	Parameter	Condition	Min	Тур	Max	Unit
PCIe Interfa	ce I/O pins				-	
VIH	Input high voltage (VDDIO)	VDDIO=1.8V	1.27	-	-	v
VIL	Input low voltage (V _{DDIO})	VDDIO=1.8V	-	-	0.58	V
Vон	Output High Voltage @ 2mA	VDDIO=1.8V	1.4	-	-	V
Vol	Output Low Voltage @ 2mA	VDDIO=1.8V	-	-	0.45	V
Vih	Input high voltage (VDDIO)	VDDIO=3.3V	0.625xVDDIO	-	-	V
VIL	Input low voltage (VDDIO)	VDDIO=3.3V	-	-	0.25xVDDIO	V
Vон	Output High Voltage @ 2mA	VDDIO=3.3V	0.75xVDDIO	-	-	V
Vol	Output Low Voltage @ 2mA	VDDIO=3.3V	-	-	0.125xVDDIO	v
Other Digita	II I/O pins					
VIH	Input high voltage (VDDIO)	VDDIO=1.8V	0.65xVDDIO	-	-	V
VIL	Input low voltage (VDDIO)	VDDIO=1.8V	-	-	0.35xVDDIO	V
V _{он}	Output High Voltage @ 2mA	VDDIO=1.8V	VDDIO-0.45	-	-	V
Vol	Output Low Voltage @ 2mA	VDDIO=1.8V	-	-	0.45	V
VIH	Input high voltage (VDDIO)	VDDIO=3.3V	2.0	-	-	V
VIL	Input low voltage (VDDIO)	VDDIO=3.3V	-	-	0.8	V
Vон	Output High Voltage @ 2mA	VDDIO=3.3V	VDDIO-0.4	-	-	V
V _{OL}	Output Low Voltage @ 2mA	VDDIO=3.3V	-	-	0.4	V



3.4 Power up Timing Sequence

3.4.1 Sequencing of Reset and Regulator Control Signals

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The AW-CM217NF has three signals that allow the host to control power consumption by enabling or disabling the Bluetooth, WLAN, and internal regulator blocks. These signals are described below. Additionally, diagrams are provided to indicate proper sequencing of the signals for various operational states. The timing values indicated are minimum required values; longer delays are also acceptable. **Note:**

- For both the WL_REG_ON and BT_REG_ON pins, there should be at least a 10 ms time delay between consecutive toggles (where both signals have been driven low). This is to allow time for the CBUCK regulator to discharge. If this delay is not followed, then there may be a VDDIO in-rush current on the order of 36 mA during the next PMU cold start.
- VBAT should not rise 10%–90% faster than 40 microseconds. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

3.4.2 Description of Control Signals

The AW-CM217NF has two signals that enable or disable the Bluetooth and WLAN circuits and the internal regulator blocks, allowing the host to control power consumption.

PIN No.	Name	Description	Туре
45	WL_REG_ON	Used by PMU to power up or power down the internal AW-CM217NF regulators used by the WLAN section. Also, when deasserted, this pin holds the WLAN section in reset. This pin has an internal 200 k Ω pull-down resistor that is enabled by default. It can be disabled through programming.	I
63	BT_REG_ON	Used by PMU to power up or power down the internal AW-CM217NF regulators used by the Bluetooth section. Also, when deasserted, this pin holds the Bluetooth section in reset. This pin has an internal 200 k Ω pull-down resistor that is enabled by default. It can be disabled through programming.	I

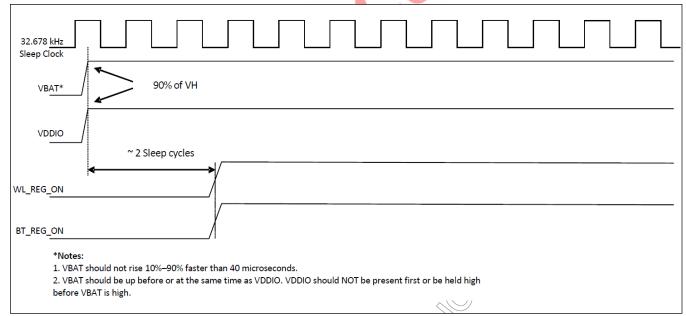


Power-Up/Power-Down/Reset Control Signals

Signal	Description
WL_REG_ON	This signal is used by the PMU (with BT_REG_ON) to power up the WLAN section. It is also ORgated with the BT_REG_ON input to control the internal AW- CM217NF regulators. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low, the WLAN section is in reset. If BT_REG_ON and WL_REG_ON are both low, the regulators are disabled. This pin has an internal 200 k Ω pull-down resistor that is enabled by default. It can be disabled through programming.
BT_REG_ON	This signal is used by the PMU (with WL_REG_ON) to decide whether or not to power down the internal AW-CM217NF regulators. If both BT_REG_ON and WL_REG_ON are low, the regulators will be disabled. When this pin is low and WL_REG_ON is high, the BT section is in reset. This pin has an internal 200 k Ω pull-down resistor that is enabled by default. It can be disabled through programming.

3.4.3 Control Signal Timing Diagrams

WLAN = ON, Bluetooth = ON



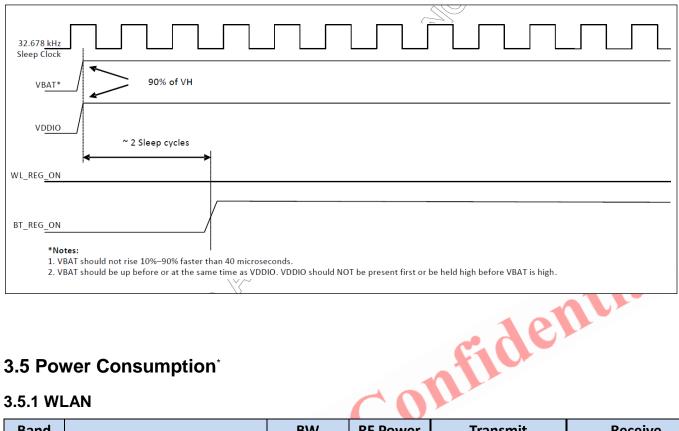
WLAN = OFF, Bluetooth = OFF



32.678 kHz Sleep Clock
VBAT*
VDDIO
WL_REG_ON
BT_REG_ON
*Notes: 1. VBAT should not rise 10%–90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.
WLAN = ON, Bluetooth = OFE
32.678 kHz Sleep Clock
VBAT* 90% of VH
VDDIO ~ 2 Sleep cycles
WL_REG_ON
BT_REG_ON
*Notes:
1. VBAT should not rise 10%–90% faster than 40 microseconds. 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.
2. VDAT should be up before of at the same time as VDDO. VDDO should not be present inst of be neit high before vDAT is high.

WLAN = OFF, Bluetooth = ON





3.5 Power Consumption*

3.5.1 WLAN

Band	Mode	BW	RF Power	Trans	smit	Receive	
(GHz)	Widde	(MHz)	(dBm)	Max.	Avg.	Max.	Avg.
	11b@1Mbps1 🤇	20	16	328.6	322.5	62.2	61.2
	11g@54Mbps 🛛 🔨 🎽	20	14	285.9	284.1	61.7	60.6
2.4	11n@MCS7	20	13	274.3	272.4	61.8	59.8
	11n@MCS7 🍆 🔪	40	11	268.6	267.9	80.8	78.6
	11n@MCS15 MIMO	40	11	465.6	464.5	122.2	120.7
	11a@54Mbps	20	13	279.8	279.4	77.4	77.1
	11n@MCS7	20	12	267.7	266.9	77.1	76.8
5	11n@MCS7	40	10	280.0	279.2	95.8	95.5
	11ac@MCS9 SISO	80	8	311.4	310.4	128.3	128.0
	11ac@MCS9 MIMO	80	8	519.8	518.1	213.3	212.5

*Current Unit: mA

3.5.2 Bluetooth

No.	Mode	Packet Type	VBAT_IN=3.3 V	
NO.	Widde	Facket Type	Max.	Avg.
1	Sleep	n/a	3.0 mA /Note 1	
2	Transmit	DH5	25.0 mA	24.5 mA



3	Receive	3-DH5	16.9 mA	16.7 mA
4	AirPlane *(3)	n/a	1.5 mA	1.5 mA

*Current Unit: mA

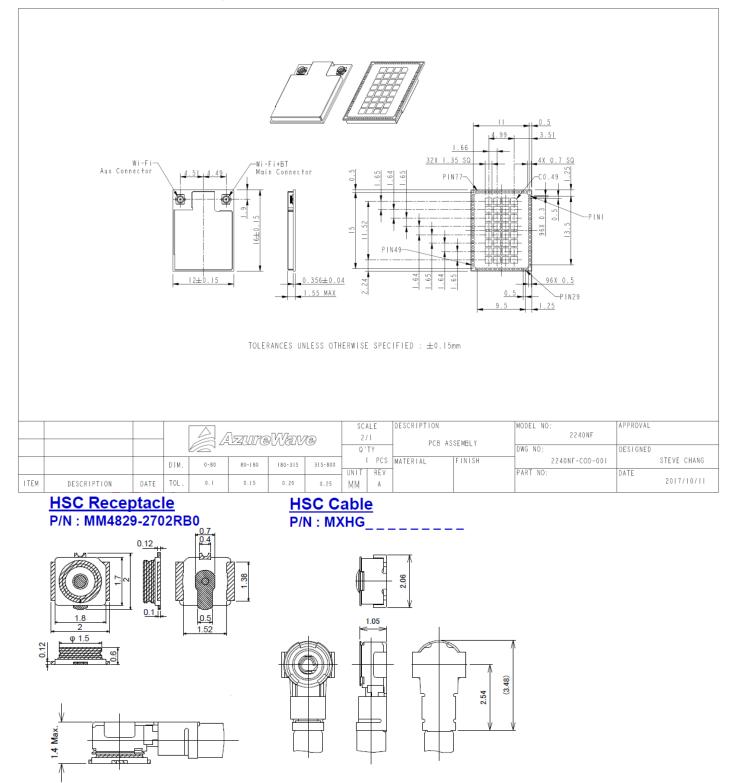
* The power consumption is based on Azurewave test environment, these data for reference only.

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4. Mechanical Information

4.1 Mechanical Drawing



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5. Packaging Information



PINK BUBBLE WRAP







AFFIX PACKING LABEL



